

CALL FOR PAPERS

IMPORTANT DATES

January 30, 2023

Submission open

March 31, 2023

Abstract submission deadline

May 22, 2023

Author notification

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The 2023 IEEE International Ultrasonics Symposium will be the 61st edition of this conference and will be held on **September 3-7, 2023 in Montreal, Canada** at the Palais des congrès de Montréal. Montréal is famous for its special blend of international cultures and Euro-American charm. It is consistently ranked as one of the top host cities in the Americas for international meetings. This conference will include a hybrid option to provide on-line access for those attending virtually.

As a satellite event for the 2023 IEEE International Ultrasonics Symposium, a one-day Symposium on Artificial Intelligence (AI) in Ultrasonics will be held on September 8, 2023 at the same venue. Montréal is internationally known as a hub for AI research and development with the largest AI academic community in the world.

Opening Plenary: “Deep Learning and the Challenge of Out-of-Distribution Generalization” by Professor Yoshua Bengio, University of Montreal, one of the founding fathers of deep learning and the recipient of the 2018 Turing Award.

Submission Topics

Abstracts should be submitted according to the information posted on the conference web page. Each abstract will receive careful review and evaluation by the symposium Technical Program Committee based on originality of the work, contribution to the state of the art and overall interest to the ultrasonics community. Papers are solicited describing original work in the field of ultrasonics.

- » **Group 1: Medical Ultrasonics**
- » **Group 2: Sensors, NDE & Industrial Applications**
- » **Group 3: Physical Acoustics**
- » **Group 4: Microacoustics – SAW, FBAR & MEMS**
- » **Group 5: Transducers & Transducer Materials**

Student Paper Competition and Travel Support

Students submitting abstracts are invited to participate in a student paper competition. To participate, the student must be the lead author and present their paper. Limited funds are available to support travel for IEEE UFFC student member attendees at the 2023 symposium. Awards will be given on a competitive basis. Please see the conference website for details on these opportunities for students.